SDLS070

DECEMBER 1972-REVISED MARCH 1988

- Typical Maximum Clock Frequency . . . 39 MHz
- Three Operating Modes:

Synchronous Parallel Load Right Shift Hold (Do Nothing)

- Negative-Edge-Triggered Clocking
- D-C Coupling Symplifies System Designs

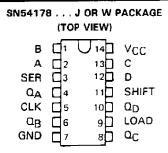
description

These shift registers utilize fully d-c coupled storage elements and feature synchronous parallel inputs and parallel outputs.

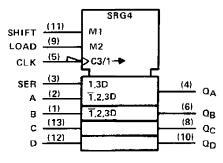
Parallel loading is accomplished by taking the shift input low, applying the four bits of data, and taking the load input high. The data is loaded into the associated flip-flop synchronously and appears at the outputs after a high-to-low transition of the clock. During loading, serial data flow is inhibited.

Shift right is also accomplished on the falling edge of the clock pulse when the shift input is high regardless of the level of the load input. Serial data for this mode is entered at the serial data input.

When both the shift and load inputs are low, clocking of the register can continue; however, data appearing at each output is fed back to the flip-flop input creating a mode in which the data is held unchanged. Thus, the system clock may be left free-running without changing the contents of the register.



lagic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617.12.

FUNCTION TABLE

INPUTS							OUTPUTS					
SHIFT	LOAD	CLOCK	SERIAL	PARALLEL				۵.	0-		a _o	
				Α	8	С	D	QA.	αB	αc	40	
Х	Х	Н	Х	х	Х	Х	Х	Q _{AQ}	α _{B0}	₫C0	ODO	
L	L	1	х	х	Х	Х	Х	QAO	σ_{BO}	a_{C0}	σ_{D0}	
L	H	↓	X	а	b	c	d	a	b	С	đ	
Н	Х	1	н	х	Х	Х	Х	н	σ_{An}	a_{Bn}	a_{Cn}	
Н	х	↓ ↓	L	х	Х	Х	Х	Ł	QAn	a_{Bn}	α_{Cn}	

H = high level (steady state), L = low level (steady state)



X = irrelevant (any input, including transitions)

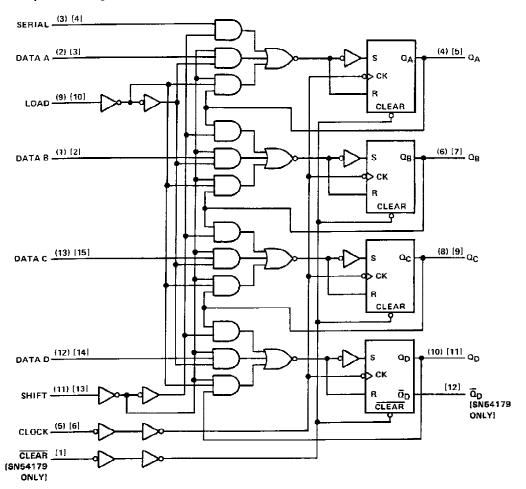
^{1 =} transition from high to low level

a, b, c, d = the level of steady-state input at inputs A, B, C, or D, respectively.

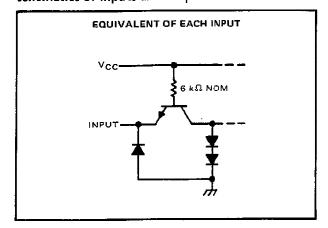
 Q_{A0} , Q_{B0} , Q_{C0} , Q_{D0} = the level of Q_{A} , Q_{B} , Q_{C} , or \overline{Q}_{D} , respectively, before the indicated steady-state input conditions were established.

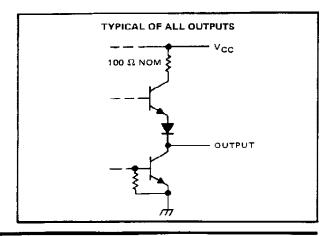
 Q_{An} , Q_{Bn} , Q_{Cn} = the level of Q_{A} , Q_{B} , or Q_{C} , respectively, before the most-recent 1 transition of the clock.

logic diagram (positive logic)



schematics of inputs and outputs







NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		T	SN5417	8	SN74178			UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT		
Supply voltage, VCC		4.5	5	5.5	4.75	5	5.25	٧		
High-level output current, IOH				-800			-800	μА		
Low-level output current, IQL		İ		16			16 m			
Clock frequency, fclock		0		25	0		25	25 MHz		
Width of clock or clear pulse, tw (see	Figure 11	20			20			ns		
	Shift (H or L) or load	35			35					
Setup time t _{su} (see Figure 1)	Data	30			30			กร		
Hold time at any input, th		5			5			ns		
Operating free-air temperature, TA		- 55		125	0		70	°C		

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN54178			SN74178		
	PARAMETER	TEST CONDITIONS†	MIN	TYP‡	MAX	MIN	TYP‡	MAX	TINU
ViH	High-level input voltage		2			2			V
VIL	Low-level input voltage			-	0.8	{		0.8	٧
VIK	Input clamp voltage	V _{CC} = MIN, I _I = -12 mA			-1.5			-1.5	٧
v _{OH}	High-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = -800 μA	2.4	3.4		2.4	3.4		٧
VOL	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{DL} = 16 mA		0.2	0.4		0.2	0.4	V
1 ₁	Input current at maximum input voltage	V _{CC} = MAX, V ₁ = 5.5 V			1			1	mΑ
ΊΗ	High-level input current	VCC = MAX, VI = 2.4 V			40			40	μА
IJĹ	Low-level input current	VCC = MAX, VI = 0.4 V		·	1.6			-1.6	mA
los	Short-circuit output current \$	V _{CC} = MAX	-20		-57	-18		-67	mΑ
Icc	Supply current	V _{CC} = MAX, See Note 2		46	70		46	75	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type.

NOTE 2: I_{CC} is measured as follows:

- a) 4.5 V is applied to serial inputs, load, shift, and clear,
- b) Parallel inputs A through D are grounded.
- cl 4.5 V is momentarily applied to clock which is then grounded.

 $[\]ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C.

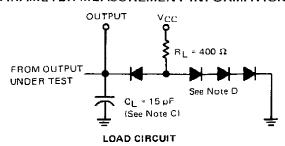
 $^{^{\}mbox{\S}}$ Not more than one output should be shorted at a time.

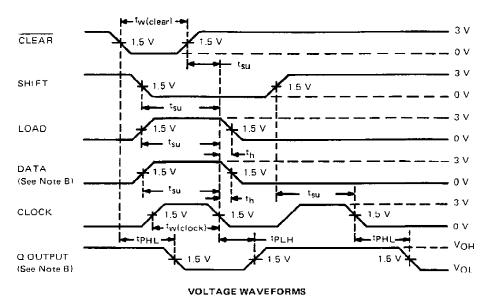
SN54178, SN74178 **4-BIT PARALLEL-ACCESS SHIFT REGISTERS**

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}				25	39		MHz
tPLH	Clear	·	C 15 pc P 400 C		15	23	ns
tPHL.	Olean	α _Α , α _Β , α _C , α _D	C _L = 15 pF, R _L = 400 Ω, See Figure 1		24	36	,,,
tPLH	Clack	Any output	See Figure 1		17	26	ns
tPHL	Oldek	Any output			23	35	''3

PARAMETER MEASUREMENT INFORMATION





- NOTES: A. Input pulses are supplied by generators having the following characteristics: $t_{TLH} \le 10 \text{ ns}$, $t_{THL} \le 10 \text{ ns}$, $PRR \le 1 \text{ MHz}$, $z_{out} \approx$ 50 Ω .
 - B. Data input and Q output are any related pair. Serial and other data inputs are at GND, Serial data input is tested in conjunction with Q_{A} output in the shift mode.
 - C. GL includes probe and jiy capacitance.
 - D. All diodes are 1N3064 or equivalent,

FIGURE 1-SWITCHING TIMES



[†]f_{max} = Maximum clock frequency tpHL = Propagation delay time, high-to-low-level output

tpLH = Propagation delay time, low-to-high-level output

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